



## Product Change Notification: DSNO-05FWOH777

**Date:**

07-Jan-2026

**Product Category:**

Wireless Modules

**Notification Subject:**

CCB 7985 Final Notice: Qualification of MMT as an additional assembly site for AT86RF212B-ZU, AT86RF212B-ZUR, AT86RF231-ZF, AT86RF231-ZFR, AT86RF231-ZU, AT86RF231-ZUR, AT86RF232-ZX, AT86RF232-ZXR, AT86RF233-ZF, AT86RF233-ZFR, AT86RF233-ZU and AT86RF233-ZUR available in 32L VQFN (5x5x0.9mm) package.

**Affected CPNs:**

[DSNO-05FWOH777\\_Affected\\_CPN\\_01072026.pdf](#)

[DSNO-05FWOH777\\_Affected\\_CPN\\_01072026.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of MMT as an additional assembly site for AT86RF212B-ZU, AT86RF212B-ZUR, AT86RF231-ZF, AT86RF231-ZFR, AT86RF231-ZU, AT86RF231-ZUR, AT86RF232-ZX, AT86RF232-ZXR, AT86RF233-ZF, AT86RF233-ZFR, AT86RF233-ZU and AT86RF233-ZUR available in 32L VQFN (5x5x0.9mm) package.

**Pre and Post Summary Changes:**

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Amkor Technology Philippines	Amkor Technology Philippines	Microchip Technology Thailand	Yes

	(P3/P4), INC. (ATP7)	(P3/P4), INC. (ATP7)	(Branch) (MMT)	
<b>Wire Material</b>	AuPd	AuPd	CuPdAu	Yes
<b>Die Attach Material</b>	AMK-06 (PFAS-free)	AMK-06 (PFAS-free)	QMI519 (PFAS-free)	Yes
<b>Molding Compound Material</b>	G700	G700	G700LTD	Yes
<b>Lead-Frame Material</b>	C194	C194	C194	No
<b>Lead-Frame Paddle Size</b>	130 x 130 mils	130 x 130 mils	150 x 150 mils	Yes
<b>Lead-Frame Lead Lock</b>	No	No	Yes	Yes
<b>Lead-Frame Design</b>	See Pre and Post Change Summary attachment for comparison.			

### Impacts to Datasheet: None

## Change Impact: None

**Reason for Change:** To improve on time delivery performance by qualifying MMT as an additional assembly site.

### **Change Implementation Status: In Progress**

**Estimated First Ship Date:** 18 March 2026 (date code: 2612)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

## Timetable Summary:

<b>Estimated Implementation Date</b>								X		
--------------------------------------	--	--	--	--	--	--	--	---	--	--

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_{PCN}\_Qual\_Report.

**Revision History:** January 07, 2026: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### **Attachments:**

[\*\*PCN\\_DSNO-05FWOH777\\_Pre and Post Change Summary.pdf\*\*](#)  
[\*\*PCN\\_DSNO-05FWOH777\\_Qual\\_Report.pdf\*\*](#)

Please contact your local [\*\*Microchip sales office\*\*](#) with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [\*\*PCN home page\*\*](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [\*\*PCN FAQ\*\*](#) section.

If you wish to change your PCN profile, including opt out, please go to the [\*\*PCN home page\*\*](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.